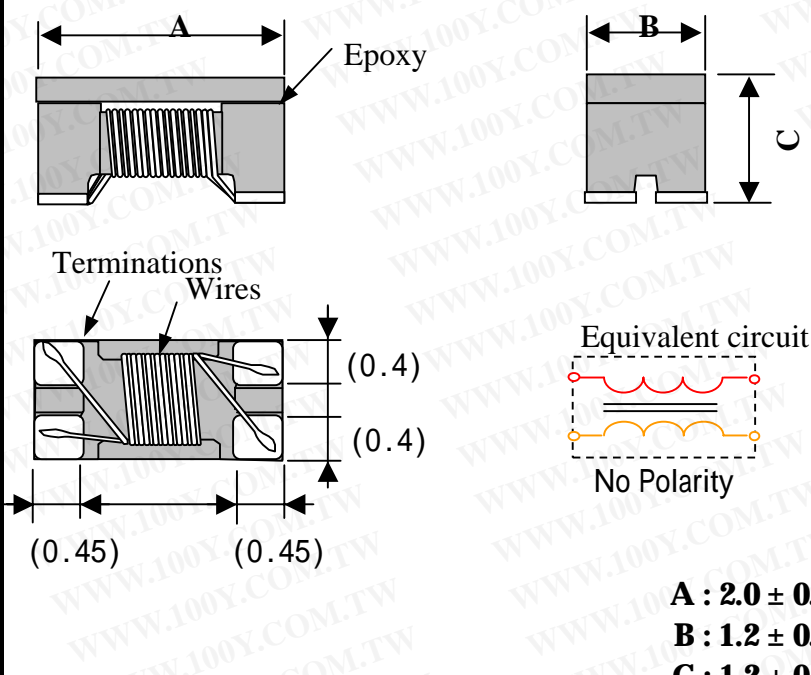


DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T
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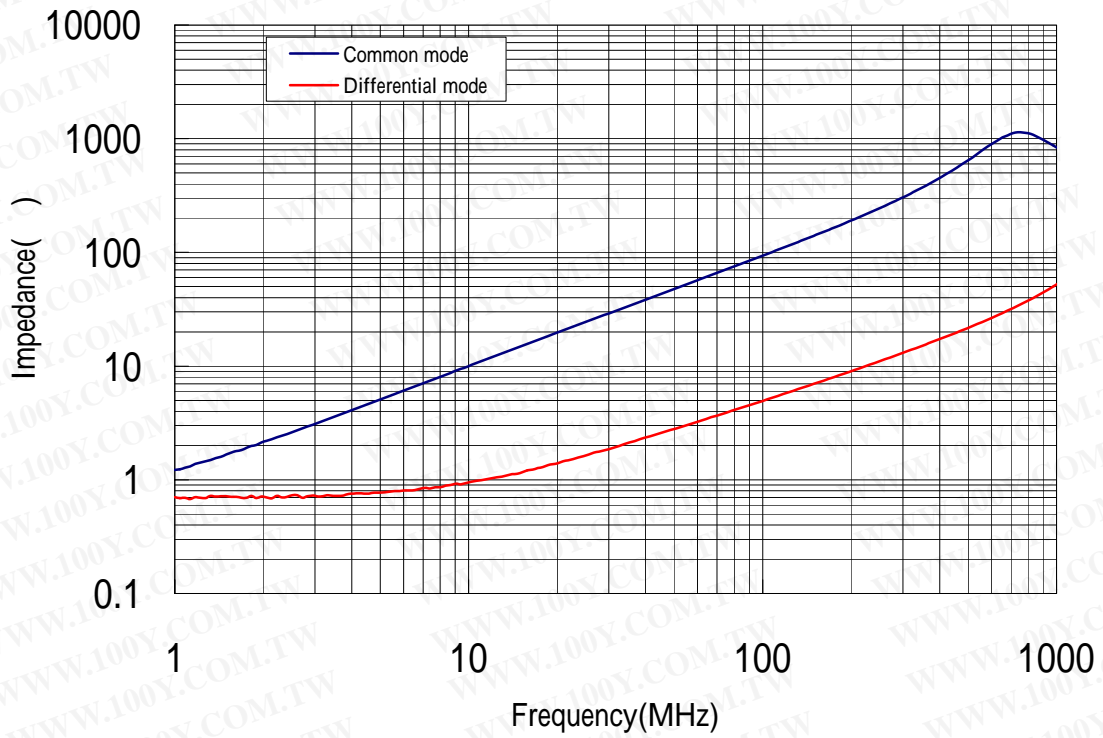
SHAPES & DIMENSIONS	ELECTRICAL CHARACTERISTICS	
 <p><b>A : 2.0 ± 0.2</b>  <b>B : 1.2 ± 0.2</b>  <b>C : 1.2 ± 0.2</b></p>	IMPEDANCE (Ω)	90Ω ± 25%
	DCR	0.35Ω (Max.)
	RATED CURRENT	330mA (Max.)
	RATED VOLTAGE	50VDC
	Insulation Resistance (MΩ)	10 (Min.)
<b>ORDERING CODE :</b>  CUBF - T4P - 2012 - _____ T (1) (2) (3) (4) (5)  <b>(1) Product Code</b> <b>(2) Number of Pins</b> <b>(3) Size Code</b> <b>(4) Impedance Value Code</b> <b>(5) Taping</b>	<b>TEST FREQUENCY</b>	
	100 MHz	
	<b>TEST EQUIPMENT</b>	
	IMPEDANCE TEST BY E4991A DCR TEST BY CH-16502	



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### Characteristics(Reference)

CUBF-T4P-2012-900T

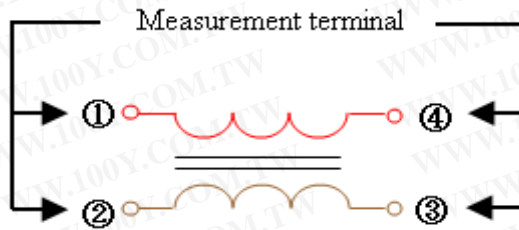


DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T

## Test Equipment

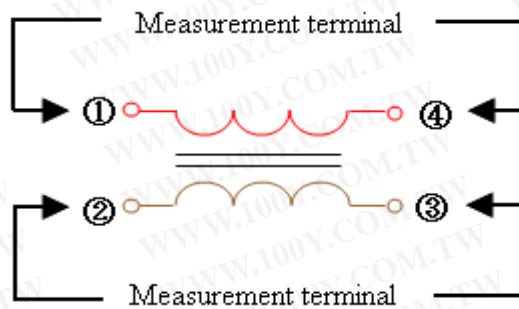
### 1. Impedance

Measured by using Agilent E4991A RF Impedance Analyzer.



### 2. DC Resistance

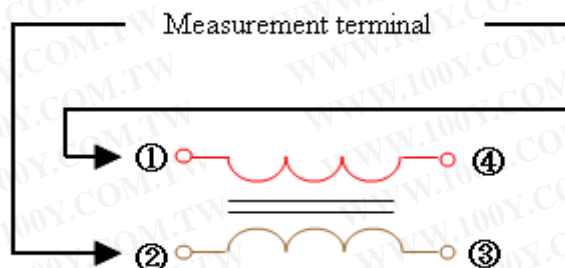
Measured by using Chroma 16



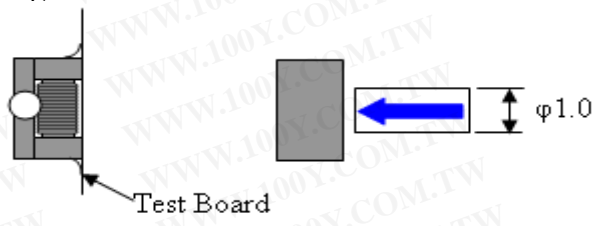
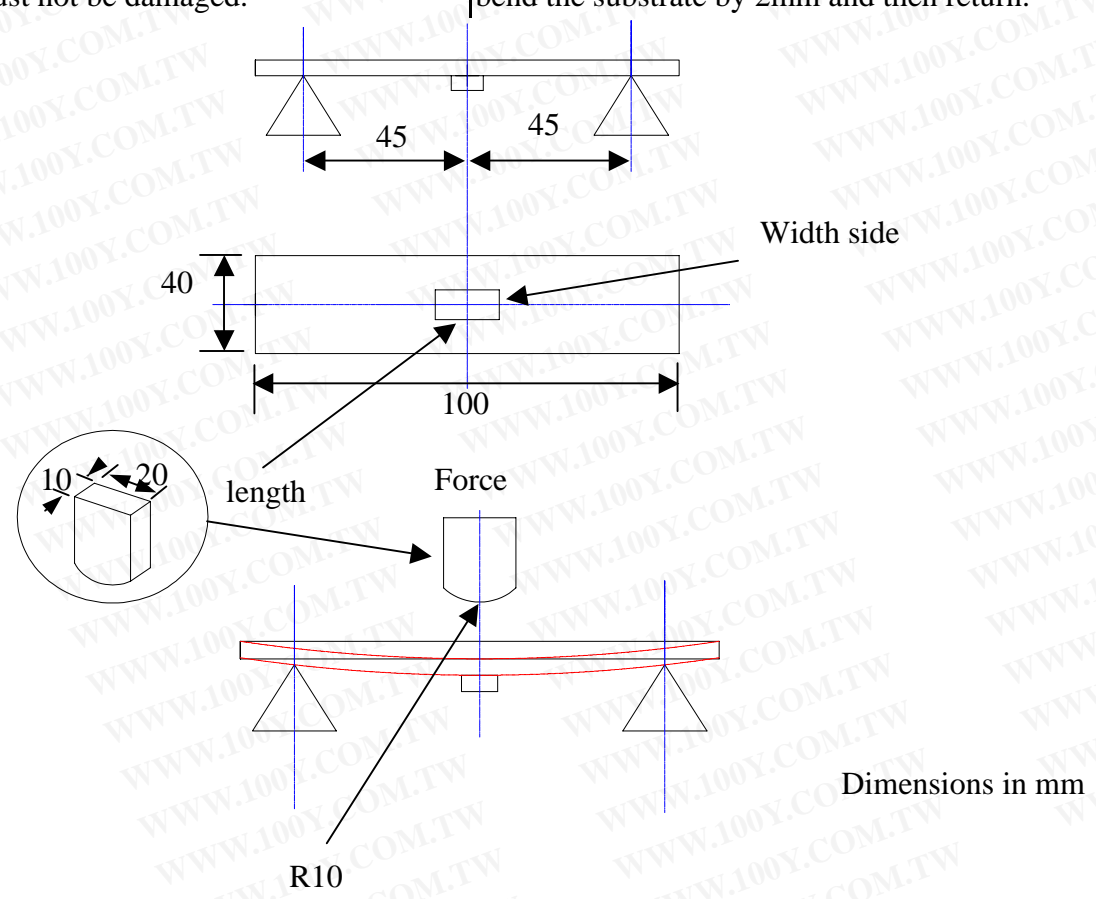
### 3. Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v .

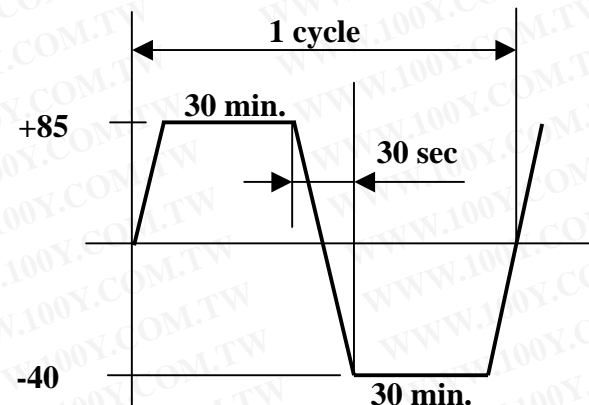


DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T
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Operating temperature : -25 to +85		Storage temp and humidity : 20~25 ,60%RH max.
Item	Specifications	Test conditions
Solder ability	It can be connected on the Recommendation soldering condition.	Apply cream solder to the test circuit board . It is mounted on the recommendation soldering condition. Dip pads in flux and dip in solder pot( 96.5 Sn/3.5 Ag solder) at 255°C ±5°C.
Terminal strength	The terminal electrode and the ferrite must not be damaged.	Solder a chip to test substrate , and then laterally apply a load 0.5Kg in the arrow direction. 
Strength on pc board bending	The terminal electrode and the ferrite must not be damaged.	Soldering a chip to a test substrate , bend the substrate by 2mm and then return.  <p>Dimensions in mm</p> <p>R10</p> <p>Test board : Glass base epoxy multiplayer board pc board pattern. PC board pattern : Recommended PC board pattern.</p>



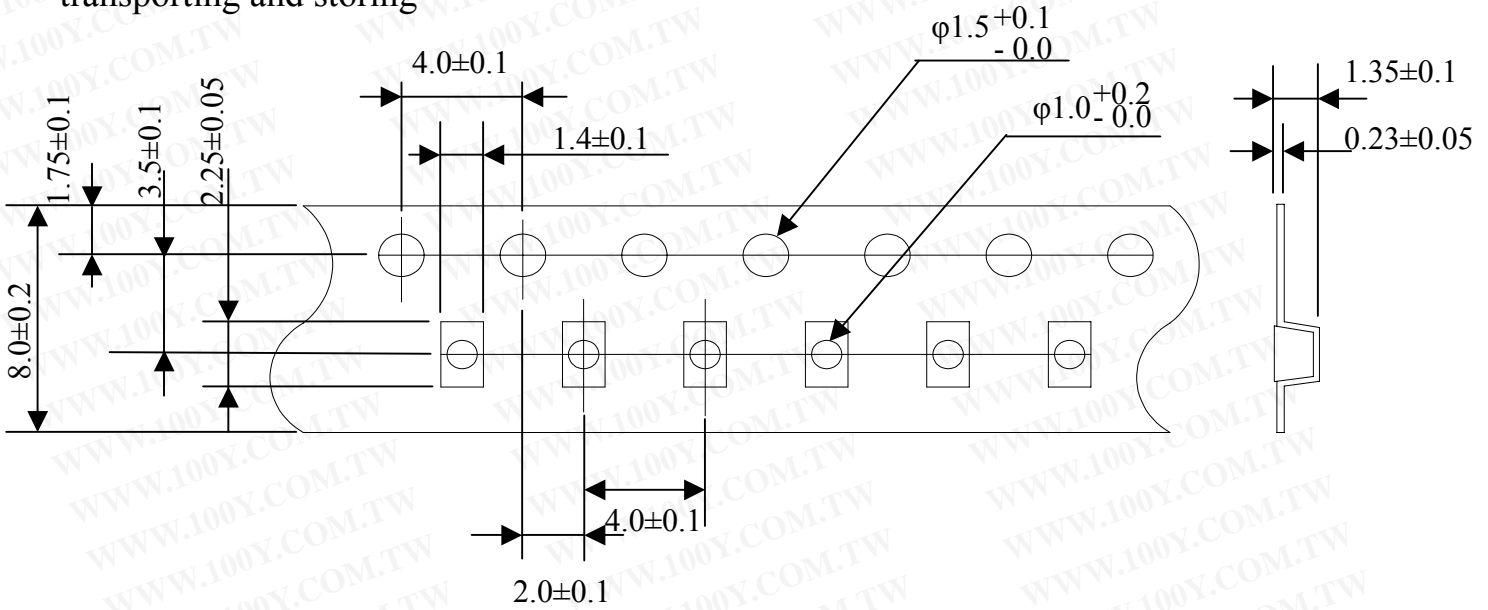
DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T
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Item	Specifications	Test conditions
High temperature resistance	Appearance : Ferrite shall not be damaged.  initial value. insulation resistance: >10(MΩ) DC resistance : standard value	Temperature : +85±2 Applied voltage : Rated voltage Applied current : Rated current Testing time : 50±12 hours Measurement : After placing for 24 hours min.
Humidity resistance	inside.	Temperature : +85±2 Humidity : 90 to 95%RH Applied current : Rated current Applied voltage : Rated voltage Testing time : 500±12 hours Measurement : After placing for 24 hours min.
Thermal shock		Temperature : -25 ,+85 kept stabilized for 30 minutes each. Cycle : 100 cycle Measurement : After placing for 24 hours min.  
Low temperature resistance		Temperature : -25±2 Testing time : 48±12 hours Measurement : After placing for 24 hours min.
Vibration	Appearance : Ferrite shall not be damaged.	Frequency : 10 to 50 Hz Amplitude : 1.52 mm Dimension and times : X ,Y and Z directions for 2 hours each.

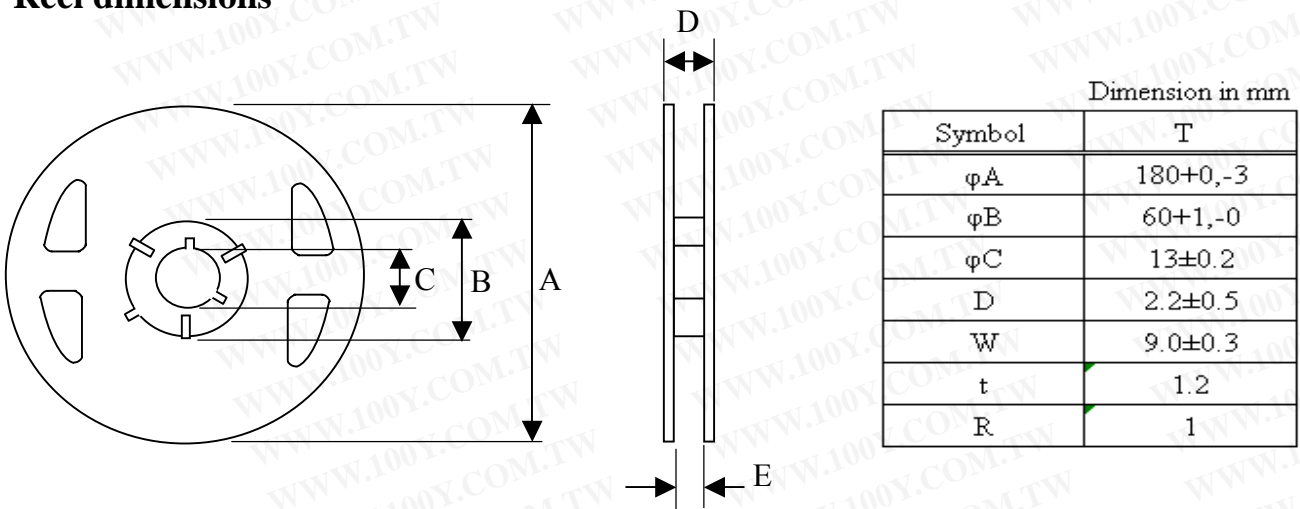
DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T
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## Packaging

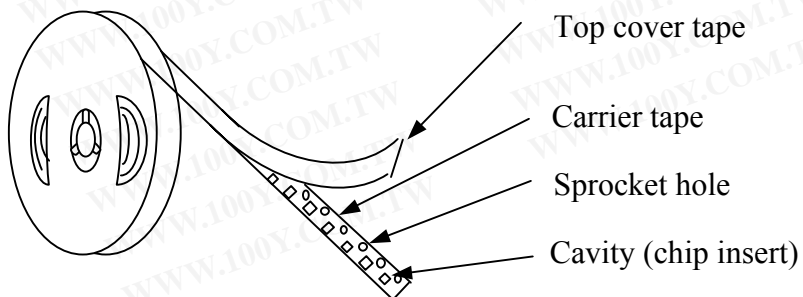
The packaging must be done not to receive any damage during transporting and storing



## Reel dimensions



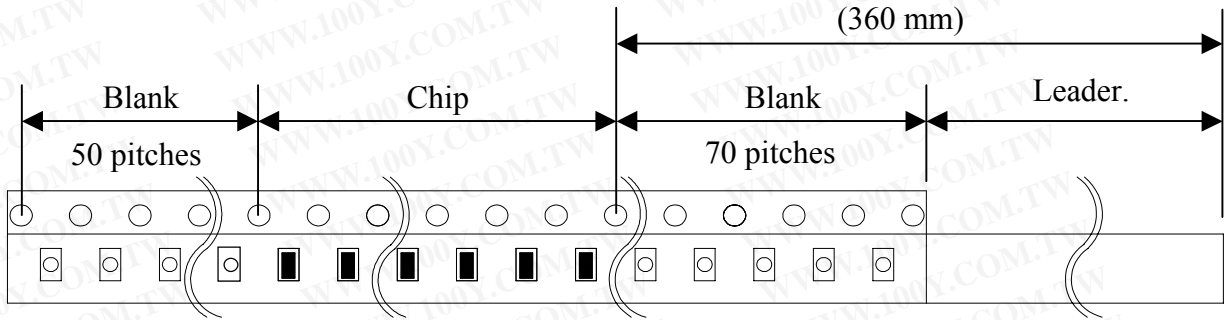
## Tapping figure



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**Packaging Form**

There shall not continuation more than two vacancies of the product.



**Material of carrier tape : Polyst**

**Material of cover tape : Polyest**

**Cover Tape Peel Strength**

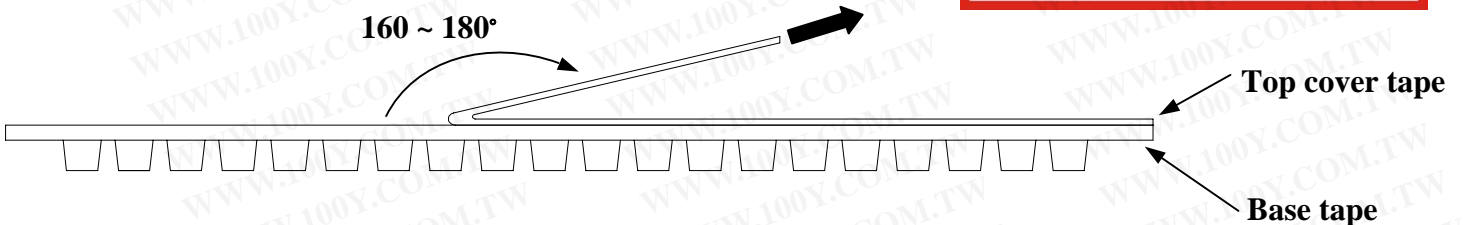
The force for tearing off cover tape is 0.05~0.69(N) in the arrow direction at the following conditions:

Temperature : 5 ~ 35

Humidity : 45 ~ 85%

Atmospheric pressure : 860 ~ 1060 hpa

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**Packing Quantity**

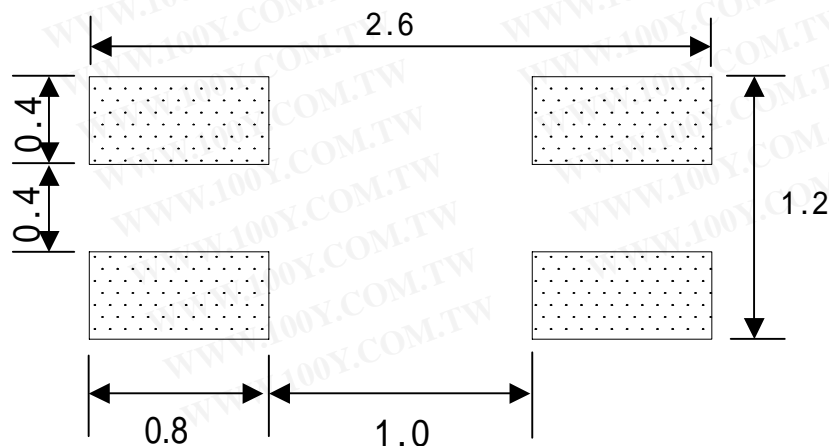
φ180 mm reel T type : 3000 pcs./reel

**Recommended Soldering Conditions**

(Please use this product by reflow soldering)

**\*Recommended Footprint**

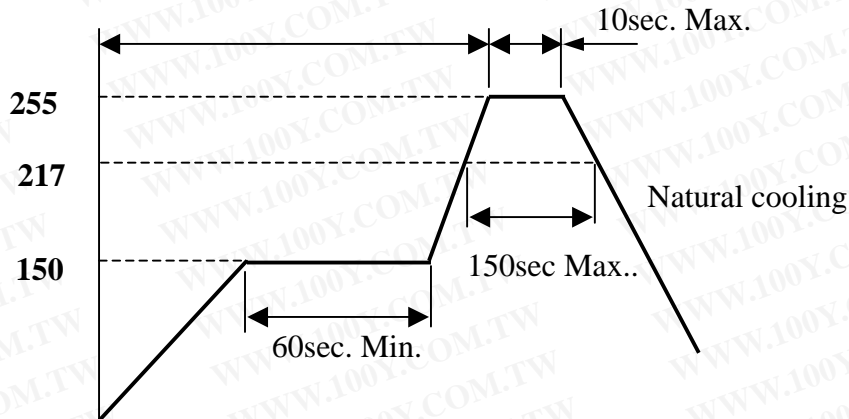
Termination Number : Please refer to the equivalent circuit in chapter 3.



DOCUMENT	SPECIFICATION FOR APPROVAL	PART	CUBF-T4P-2012-900T

**\*Recommended Reflow Pattern**

Reflow : until two times



**\* Iron Soldering**

Use a solder iron of less than 30W when soldering ,do not allow the soldering iron tip directly touch the ferrite body outside of terminal electrode.  
4 seconds max. at 260 .

**Attention in Case of Using**

In case of using product ,please avoid following matters:

Splashing water or salt water

Dew condens

Toxic gas (Hydrogen sulfide, Sulfurous acid ,Chlorine, Ammonia)

Vibrations or shocks which exceed the specified conc

Please be careful for the stress to this product by board fle after the mounung.

**Others**

\*Operating temperature range : -25~ + 85

\*Storage condition : Temperature 20~25 , Relative Humidity 40% ~ 60%

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